

Application Data Sheet

Application Information

Application Type:: Regular
Subject Matter:: Utility
Suggested Classification::
Suggested Group Art Unit::
CD-ROM or CD_R?:: Table
Number of CD disks::
Number of copies of CDs::
Sequence Submission:: No
Computer Readable Form (CRF)?:: No
Title:: METHOD OF FABRICATING A MULTI-LAYER
CIRCUIT BOARD ASSEMBLY
Attorney Docket Number:: 8688.258US01
Request For Early Publication:: No
Request For Non-Publication:: No
Suggested Drawing Figure::
Total Drawing Sheets:: 3
Small Entity:: No
Latin Name::
Variety Denomination Name::
Petition Included:: No
Petition Type::
Licensed US Govt. Agency::
Contract or Grant Numbers::
Secrecy Order in Parent Appl.?:: No

Initial 01/15/02

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship:: Taiwan
Country:: Taiwan
Status:: Full Capacity
Given Name:: Yu-Chiang
Middle Name::
Family Name:: CHENG
Name Suffix::
City of Residence:: Taipei City
State or Province of Residence::
Country of Residence:: Taiwan
Street of mailing address:: 3F, No. 17, Alley 5, Lane 257, Kung-Kuan Rd.,
Pei-Tou Dist.
City of mailing address:: Taipei City
State or Province of mailing address::
Country of mailing address:: Taiwan
Postal or Zip Code of mailing address::

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship:: Taiwan
Country:: Taiwan
Status:: Full Capacity
Given Name:: Jong-Kuei
Middle Name::
Family Name:: CHEN
Name Suffix::
City of Residence:: Hua-Lien Hsien

Initial 01/15/02

State or Province of Residence::

Country of Residence:: Taiwan

Street of mailing address:: No. 54, Chu-Tien Tsun, Fu-Li Hsiang

City of mailing address:: Hua-Lien Hsien

State or Province of mailing address::

Country of mailing address:: Taiwan

Postal or Zip Code of mailing address::

Correspondence Information

Correspondence Customer Number:: 23552

Representative Information

Representative Customer Number::	23552
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Assignee Information

Assignee Name:: Mitac International Corp.

Street of mailing address:: No. 1, R & D 2nd Rd., Science-Based Industrial
Park

City of mailing address:: Hsinchu Hsien

State or Province of mailing address::

Country of mailing address:: Taiwan

Postal or Zip Code of mailing address::